



SOT899-1

plastic thermal enhanced very thin small outline package; no leads; 2 terminals; body 3 x 2 x 0.85 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HVSON2
Package type industry code	HVSON2
Package style descriptive code	HVSON (thermal enhanced very thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	9-5-2005

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.9	-	2	2.1	mm
E	package width	2.9	-	3	3.1	mm
A	seated height	[tbd]	-	0.85	1	mm
A ₂	package height	[tbd]	-	0.85	[tbd]	mm
n ₂	actual quantity of termination	-	-	2	-	

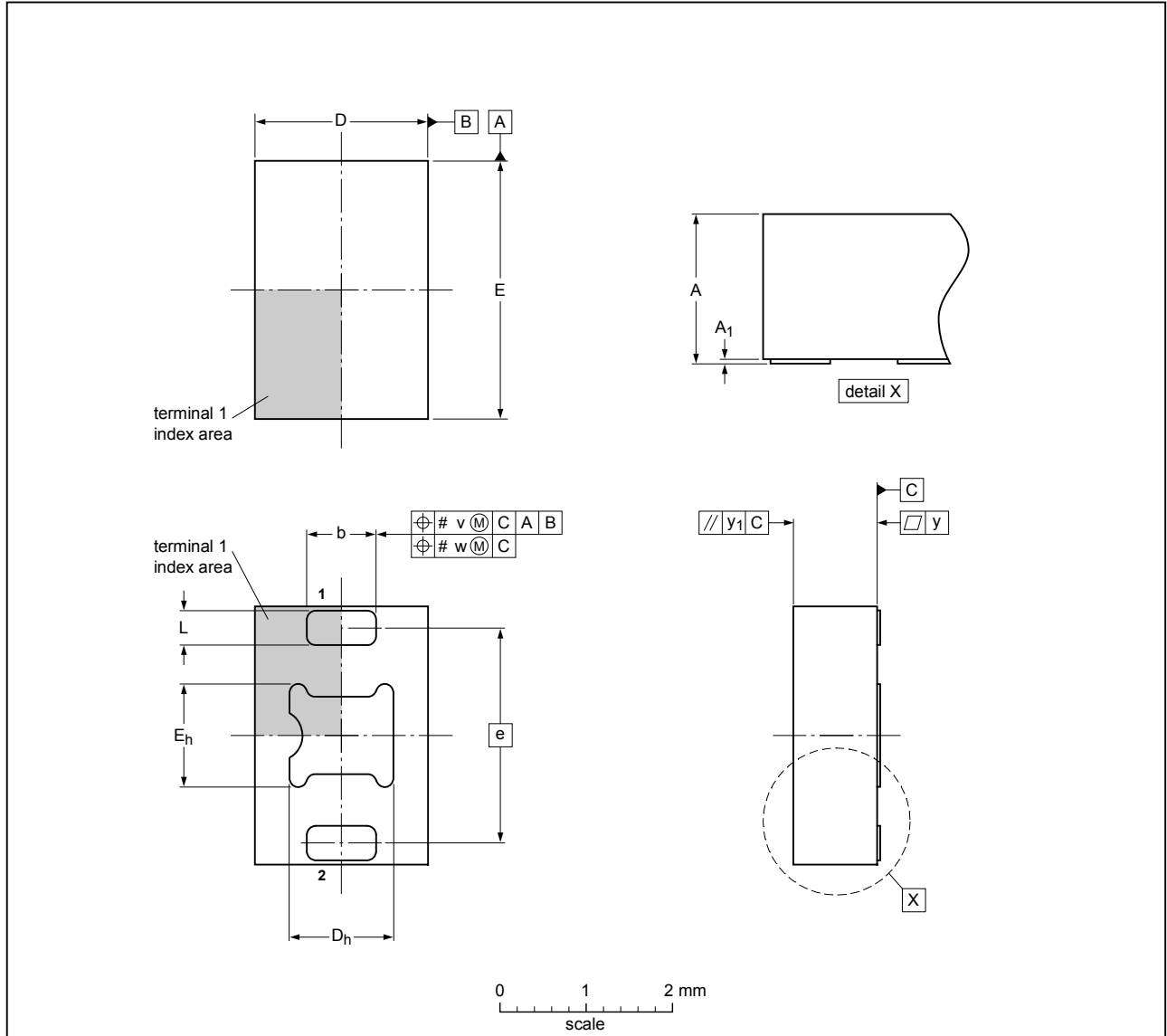


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2. Package outline

HVSON2: plastic thermal enhanced very thin small outline package; no leads; 2 terminals; body 3 x 2 x 0.85 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A _{max}	A ₁	b	D	D _h	E	E _h	e	L	v	w	y	y ₁
mm	1	0.05 0	0.9 0.7	2.1 1.9	1.35 1.05	3.1 2.9	1.35 1.05	2.5	0.5 0.3	0.1	0.05	0.05	0.1

Note

1. Plastic or metal protrusions of 0.75 mm maximum per side are not included

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT899-1					05-02-25 05-05-09

Fig. 1. Package outline HVSON2 (SOT899-1)

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mm

3. Legal information

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